Hex Inverter

74AC04, 74ACT04

General Description

The AC/ACT04 contains six inverters.

Features

- I_{CC} Reduced by 50% On 74AC Only
- Outputs Source/Sink 24 mA
- ACT04 has TTL−Compatible Inputs
- These are Pb−Free Devices

ABSOLUTE MAXIMUM RATINGS

| Parameter	Symbol	Value	Unit
Supply Voltage	V_{CC}	−0.5 to +7.0	V
DC Input Diode Current $V_I = -0.5$ V $V_I = V_{CC} + 0.5$ V	I_{IK}	 −20 +20	mA
DC Input Voltage	V_I	−0.5 to $V_{CC} + 0.5$	V
DC Output Diode Current $V_O = -0.5$ V $V_O = V_{CC} + 0.5$ V	I_{OK}	 −20 +20	mA
DC Output Voltage	V_O	−0.5 to $V_{CC} + 0.5$	V
DC Output Source or Sink Current	I_O	±50	mA
DC V_{CC} or Ground Current per Output Pin	I_{CC} or I_{GND}	±50	mA
Storage Temperature	T_{STG}	−65 to +150	°C
Junction Temperature PDIP	T_J	140	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
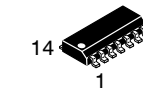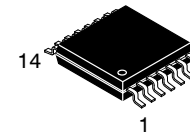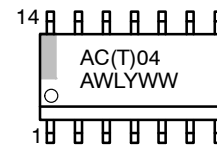
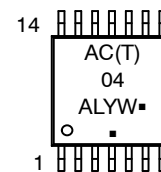**SOIC−14 NB**
CASE 751A−03
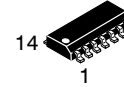
SOIC14
CASE 751EF
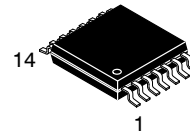
TSSOP−14 WB
CASE 948G

TSSOP−14 WB
CASE 948G−01

MARKING DIAGRAM

AC(T)04
AWLYWW

AC04, ACT04	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
Y	= Year
WW	= Work Week

MARKING DIAGRAM

AC(T)
04
ALYW■

AC04, ACT04	= Specific Device Code
A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
■	= Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ORDERING INFORMATION

Order Number	Package Number	Package Description
74AC04SC	M14A	14−Lead Small Outline Integrated Circuit (SOIC), JEDEC MS−012, 0.150" Narrow
74AC04MTC	MTC14	14−Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO−153, 4.4 mm Wide
74ACT04SC	M14A	14−Lead Small Outline Integrated Circuit (SOIC), JEDEC MS−012, 0.150" Narrow
74ACT04MTC	MTC14	14−Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO−153, 4.4 mm Wide

NOTES: Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code. All packages are lead free per JEDEC: J−STD−020B standard.
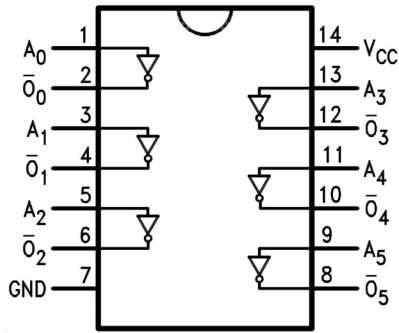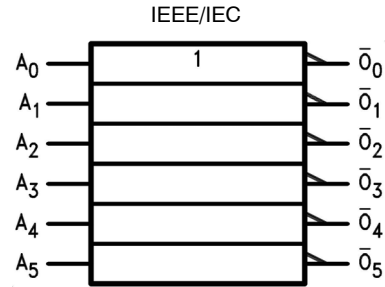

Figure 1. Connection Diagram

Figure 2. Logic Symbol

PIN DESCRIPTION

Pin	Description
A_n	Inputs
$\overline{O}_n$	Outputs

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply Voltage AC ACT	 2.0 4.5	 6.0 5.5	V
V_I	Input Voltage	0	V_{CC}	V
V_O	Output Voltage	0	V_{CC}	V
T_A	Operating Temperature	−40	+85	°C
$\Delta V / \Delta t$	Minimum Input Edge Rate, AC Devices: V_{IN} from 30% to 70% of V_{CC}, V_{CC} at 3.3 V, 4.5 V, 5.5 V	125		mV/ns
$\Delta V / \Delta t$	Minimum Input Edge Rate, ACT Devices: V_{IN} from 0.8 V to 2.0 V, V_{CC} at 4.5 V, 5.5 V	125		mV/ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS FOR AC

Symbol	Parameter	V_{CC}(V)	Conditions	T_A = +25°C		T_A = −40°C to +85°C	Unit
				Typ	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	3.0	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	2.1	2.1	V
		4.5		2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V_{IL}	Maximum LOW Level Input Voltage	3.0	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	0.9	0.9	V
		4.5		2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V_{OH}	Minimum HIGH Level Output Voltage	3.0	I_{OUT} = −50 μA	2.99	2.9	2.9	V
		4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	V_{IN} = V_{IL} or V_{IH}, I_{OH} = −12 mA	–	2.56	2.46	
		4.5	I_{OH} = −24 mA	–	3.86	3.76	
		5.5	I_{OH} = −24 mA (Note 1)	–	4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	3.0	I_{OUT} = 50 μA	0.002	0.1	0.1	V
		4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	V_{IN} = V_{IL} or V_{IH}, I_{OL} = 12 mA	–	0.36	0.44	
		4.5	I_{OL} = 24 mA	–	0.36	0.44	
		5.5	I_{OL} = 24 mA (Note 1)	–	0.36	0.44	
I_{IN} (Note 3)	Maximum Input Leakage Current	5.5	V_I = V_{CC}, GND	–	±0.1	±1.0	μA
I_{OLD}	Minimum Dynamic Output Current (Note 2)	5.5	V_{OLD} = 1.65 V Max.	–	–	75	mA
I_{OHD}		5.5	V_{OHD} = 3.85 V Min.	–	–	−75	mA
I_{CC} (Note 3)	Maximum Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND	–	2.0	20.0	μA

1. All outputs loaded; thresholds on input associated with output under test.
2. Maximum test duration 2.0 ms, one output loaded at a time.
3. I_{IN} and I_{CC} at 3.0 V are guaranteed to be less than or equal to the respective limit at 5.5 V V_{CC}.

74AC04, 74ACT04

DC ELECTRICAL CHARACTERISTICS FOR ACT

Symbol	Parameter	V_{CC}(V)	Conditions	T_A = +25°C Typ	Guaranteed Limits	T_A = −40°C to +85°C	Unit
V_{IH}	Minimum HIGH Level Input Voltage	4.5	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	2.0	2.0	V
		5.5		1.5	2.0	2.0	
V_{IL}	Maximum LOW Level Input Voltage	4.5	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	0.8	0.8	V
		5.5		1.5	0.8	0.8	
V_{OH}	Minimum HIGH Level Output Voltage	4.5	I_{OUT} = −50 μA	4.49	4.4	4.4	V
		5.5		5.49	5.4	5.4	
		4.5	$V_{IN} = V_{IL}$ or V_{IH} I_{OH} = −24 mA	−	3.86	3.76	
		5.5	I_{OH} = −24 mA (Note 4)	−	4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	4.5	I_{OUT} = 50 μA	0.001	0.1	0.1	V
		5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL}$ or V_{IH} I_{OL} = 24 mA	−	0.36	0.44	
		5.5	I_{OL} = 24 mA (Note 4)	−	0.36	0.44	
I_{IN}	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND	−	±0.1	±1.0	μA
I_{CCT}	Maximum I_{CC}/Input	5.5	$V_I = V_{CC}$ − 2.1 V	0.6	−	1.5	mA
I_{OLD}	Minimum Dynamic Output Current (Note 5)	5.5	V_{OLD} = 1.65 V Max.	−	−	75	mA
I_{OHD}		5.5	V_{OHD} = 3.85 V Min.	−	−	−75	mA
I_{CC}	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND	−	4.0	40.0	μA

4. All outputs loaded; thresholds on input associated with output under test.
5. Maximum test duration 2.0 ms, one output loaded at a time.

AC ELECTRICAL CHARACTERISTICS FOR AC

Symbol	Parameter	V_{CC}(V) (Note 6)	T_A = +25°C, C_L = 50 pF			T_A = −40°C to +85°C, C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	3.3	1.5	4.5	9.0	1.0	10.0	ns
		5.0	1.5	4.0	7.0	1.0	7.5	
t_{PHL}	Propagation Delay	3.3	1.5	4.5	8.5	1.0	9.5	ns
		5.0	1.5	3.5	6.5	1.0	7.0	

6. Voltage range 3.3 is 3.3 V + 0.3 V. Voltage range 5.0 is 5.0 V + 0.5 V.

AC ELECTRICAL CHARACTERISTICS FOR ACT

Symbol	Parameter	V_{CC}(V) (Note 7)	T_A = +25°C, C_L = 50 pF			T_A = −40°C to +85°C, C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	5.0	1.0	6.0	8.5	1.0	9.0	ns
t_{PLH}	Propagation Delay	5.0	1.0	5.5	8.0	1.0	8.5	ns

7. Voltage range 5.0 is 5.0 V + 0.5 V.

CAPACITANCE

Symbol	Parameter	Conditions	Typ	Unit
C_{IN}	Input Capacitance	V_{CC} = OPEN	4.5	pF
V_{CC}	Power Dissipation Capacitance	V_{CC} = 5.0 V	30.0	pF

SOIC−14 NB
CASE 751A−03
ISSUE L

DATE 03 FEB 2016

14

1

SCALE 1:1

DETAIL A

A3

L

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

D

14   8

H

E

1   7

⊕ | 0.25 Ⓜ | B Ⓜ

13X **b**

⊕ | 0.25 Ⓜ | C | A Ⓢ | B Ⓢ

DETAIL A

h

X 45°

M

A

▱ | 0.10

e

A1

C | **SEATING PLANE**

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

SOLDERING FOOTPRINT*

6.50

14X
1.18

1

1.27
PITCH

14X
0.58

DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*

14

XXXXXXXXXG
AWLYWW

1

XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪", may or may not be present.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

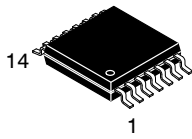| DOCUMENT NUMBER:	98ASB42565B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC−14 NB		PAGE 1 OF 2

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

DOCUMENT NUMBER:	98ASB42565B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC−14 NB		PAGE 2 OF 2

SOIC14
CASE 751EF
ISSUE O

DATE 30 SEP 2016

8.75
8.50

7.62

14   8

B

6.00

4.00
3.80

PIN #1
IDENT.

1   7

1.27   0.51
0.35

(0.33)

⊕ | 0.25 Ⓜ | C | B | A

TOP VIEW

14   0.65   8

1.70

5.60

1   1.27   7

LAND PATTERN RECOMMENDATION

1.75 MAX

1.50
1.25

0.25
0.10

C

△ | 0.10 | C

FRONT VIEW

A

0.25
0.19

SIDE VIEW
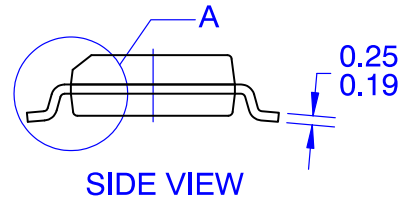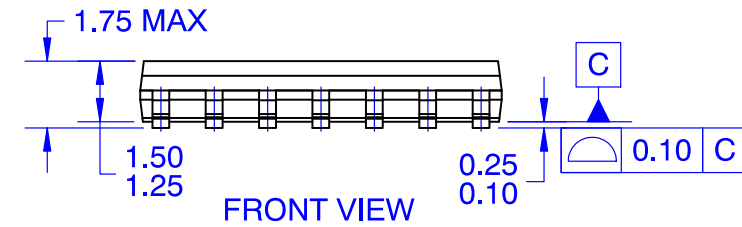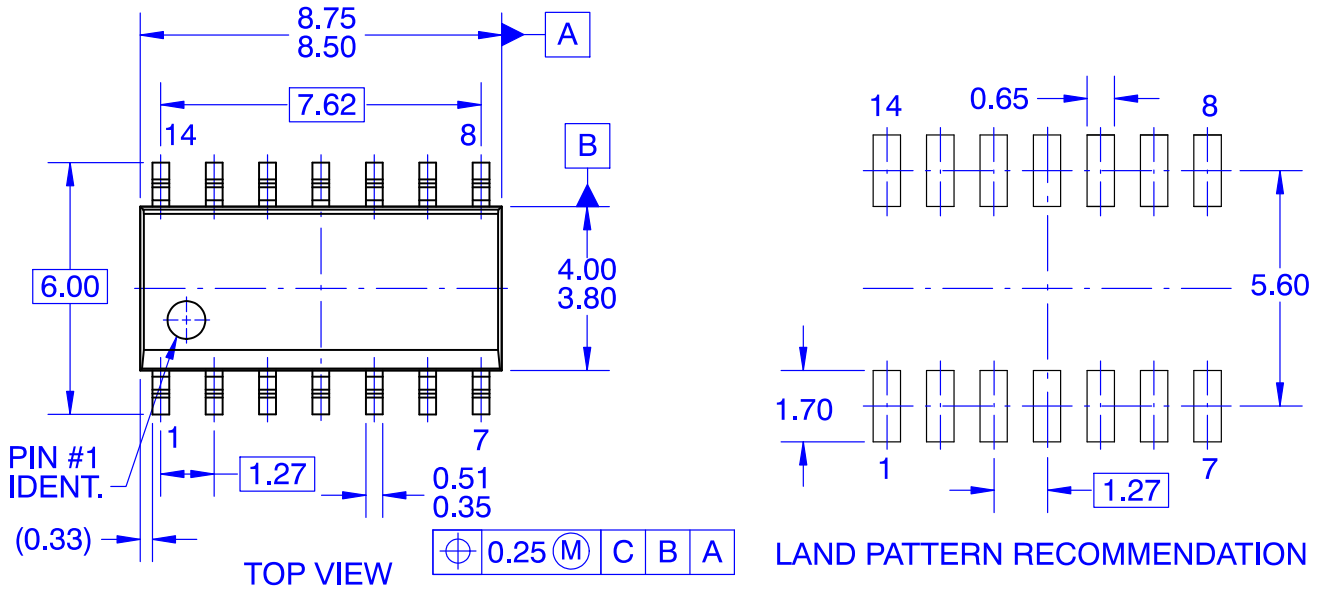
NOTES:
A. CONFORMS TO JEDEC MS−012,
   VARIATION AB, ISSUE C
B. ALL DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS DO NOT INCLUDE MOLD
   FLASH OR BURRS
D. LAND PATTERN STANDARD:
   SOIC127P600X145−14M
E. CONFORMS TO ASME Y14.5M, 2009

0.50
0.25 x 45°

R0.10

GAGE
PLANE

R0.10

0.36

8°
0°

0.90
0.50

(1.04)

SEATING PLANE
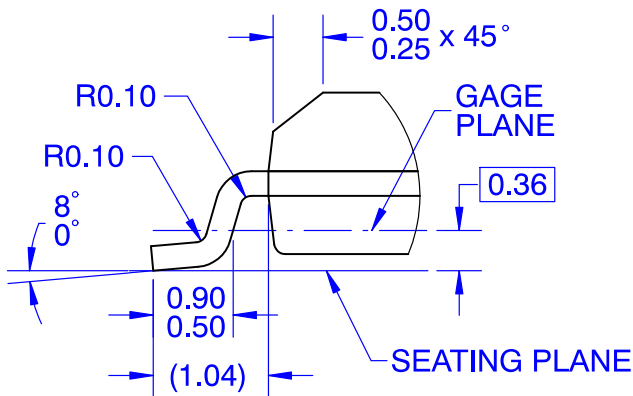
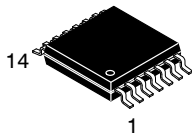**DETAIL A**
SCALE 16 : 1

DOCUMENT NUMBER:	98AON13739G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC14		**PAGE 1 OF 1**

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

TSSOP−14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016

14

SCALE 2:1

1

14X K REF

$\oplus$ | 0.10 (0.004) Ⓜ | T | U Ⓢ | V Ⓢ

$\bigtriangleup$ | 0.15 (0.006) | T | U Ⓢ

2X L/2

L

PIN 1 IDENT.

14   8

1   7

B
−U−

$\bigtriangleup$ | 0.15 (0.006) | T | U Ⓢ

A
−V−

DETAIL E

N

0.25 (0.010)

M

N

F

SECTION N−N

K

K1

J J1

C

$\bigtriangleup$ | 0.10 (0.004)
−T− SEATING PLANE

D   **G**   **H**
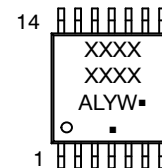
DETAIL E

−W−

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

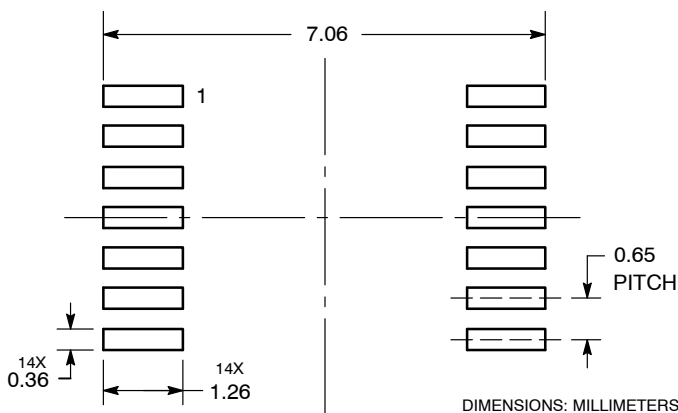|	MILLIMETERS		INCHES	
DIM	**MIN**	**MAX**	**MIN**	**MAX**
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

GENERIC MARKING DIAGRAM*

14

XXXX
XXXX
ALYW▪

1

A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪", may or may not be present.

SOLDERING FOOTPRINT

7.06

1

0.65
PITCH

14X
0.36

14X
1.26

DIMENSIONS: MILLIMETERS

TSSOP–14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016

14

SCALE 2:1

1

14X **K** REF

⊕ 0.10 (0.004) Ⓜ T U Ⓢ V Ⓢ

0.15 (0.006) T U Ⓢ

2X **L/2**

L

PIN 1
IDENT.

0.15 (0.006) T U Ⓢ

A

–V–

14   8

7

B

–U–

N

0.25 (0.010)

M

N

F

DETAIL E

K

K1

J **J1**

SECTION N–N

C

0.10 (0.004)

–T– SEATING
PLANE

D   **G**   **H**

DETAIL E

–W–

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

**GENERIC
MARKING DIAGRAM***

14

XXXX
XXXX
ALYW■

1

A   = Assembly Location
L   = Wafer Lot
Y   = Year
W   = Work Week
■   = Pb–Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present.

SOLDERING FOOTPRINT

7.06

1

0.65
PITCH

14X
0.36

14X
1.26

DIMENSIONS: MILLIMETERS

DOCUMENT NUMBER:	98ASH70246A		
DESCRIPTION:	**TSSOP–14 WB**		**PAGE 1 OF 1**

PUBLICATION ORDERING INFORMATION

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